MICROWAVE POWER GaAs FET

Internally Matched Power GaAs FETs (X, Ku-Band)

Features

- · High power
 - P_{1dB} = 36.5 dBm at 8.5 GHz to 9.6 GHz
- High gain
- G_{1dB} = 7.5 dB at 8.5 GHz to 9.6 GHz
 Broadband internally matched
- · Hermetically sealed package

RF Performance Specifications (T_a = 25°C)

| Characteristic | Symbol | Condition | Unit | Min. | Тур. | Max. |
|--|------------------|--|------|------|------|------|
| Output Power at 1dB Compression Point | P _{1dB} | V _{DS} = 9V f = 8.5 - 9.6 GHz | dBm | 35.5 | 36.5 | - |
| Power Gain at 1dB Compression Point | G _{1dB} | | dB | 6.5 | 7.5 | - |
| Drain Current | I _{DS} | | А | - | 1.7 | 2.2 |
| Power Added Efficiency | η_{add} | | % | - | 24 | - |
| Channel-Temperature Rise | ΔT_{ch} | $V_{DS} \times I_{DS} \times R_{th (c-c)}$ | °C | - | - | 70 |

Electrical Characteristics (T_a = 25°C)

| Characteristic | Symbol | Condition | Unit | Min. | Тур. | Max. |
|-------------------------------|-----------------------|---|------|------|------|------|
| Transconductance | gm | V _{DS} = 3V I _{DS} = 2.0A | mS | - | 1200 | - |
| Pinch-off Voltage | V _{GSoff} | V _{DS} = 3V I _{DS} = 60 mA | V | -2 | -3.5 | -5 |
| Saturated Drain Current | I _{DSS} | $V_{DS} = 3V$ $V_{GS} = 0V$ | А | - | 4.0 | 5.2 |
| Gate-Source Breakdown Voltage | V _{GSO} | I _{GS} = -60 μA | V | -5 | - | - |
| Thermal Resistance | R _{th (c-c)} | Channel to Case | °C/W | _ | 2.9 | 3.5 |

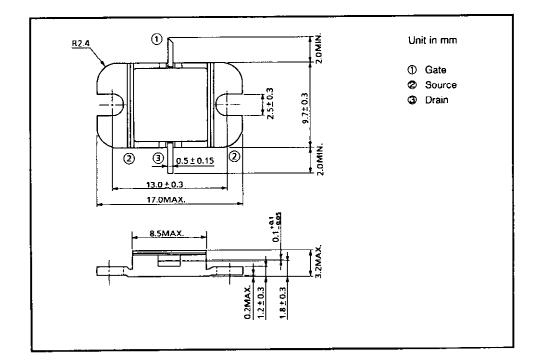
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Absolute Maximum Ratings (T_a = 25°C)

| Characteristic | Symbol | Unit | Rating |
|---|------------------|------|-----------|
| Drain-Source Voltage | V _{DS} | V | 15 |
| Gate-Source Voltage | V _{GS} | V | -5 |
| Drain Current | ۱ _D | А | 5.2 |
| Total Power Dissipation ($T_c = 25^{\circ}C$) | P _T | W | 30 |
| Channel Temperature | T _{ch} | °C | 175 |
| Storage Temperature | T _{stg} | °C | -65 ~ 175 |

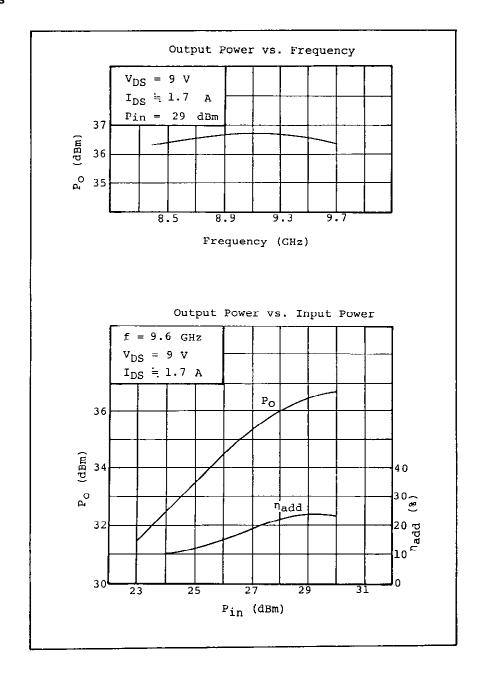
Package Outline (2-9D1B)



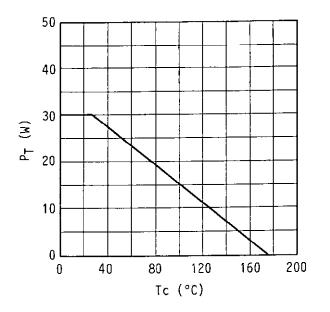
Handling Precautions for Packaged Type

Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

RF Performances



Power Dissipation vs. Case Temperature



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